

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CARMEN JIA YI SIAU	08/24/2021
KOK HONG SOON	08/24/2021
TEJEASH DURAIMANICKAM	08/25/2021
JIN HOE PHUA	08/24/2021
RECEIVING PARTY DATA	
Name:	MOTOROLA SOLUTIONS INC.
Street Address:	500 W. MONROE STREET
Internal Address:	43RD FLOOR
City:	CHICAGO
State/Country:	ILLINOIS
Postal Code:	60661
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17446630
CORRESPONDENCE DATA	
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Address Line 4:	CHICAGO, ILLINOIS 60661
ATTORNEY DOCKET NUMBER:	PAT27227-US-PRI
NAME OF SUBMITTER:	NANETTE B. ORR
SIGNATURE:	/Nanette B. Orr/
DATE SIGNED:	09/01/2021
Total Attachments: 2	

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **CARMEN JIA YI SIAU, KOTA KINABALU, MALAYSIA; KOK HONG SOON, GEORGETOWN, MALAYSIA; TEJEASH DURAIMANICKAM, LUNAS, MALAYSIA AND JIN HOE PHUA, CHENDERIANG, MALAYSIA**, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto MOTOROLA SOLUTIONS, INC., a corporation of the State of Delaware, having its principal office in Chicago, State of Illinois, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **SECURITY ECOSYSTEM** (Docket No. **PAT27227-US-PRI**) described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any nonprovisional, division, extension, continuation, reexamination or reissue thereof.

We hereby also sell, assign and transfer unto MOTOROLA SOLUTIONS, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefore in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize MOTOROLA SOLUTIONS, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, reexamination or reissue to MOTOROLA SOLUTIONS, INC., for the sole use and benefit of MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to MOTOROLA SOLUTIONS, INC.

We agree that, when requested, we will, without charge to MOTOROLA SOLUTIONS, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives or nominees.

We covenant with MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **CARMEN JIA YI SIAU**

Signature: *Carmen Siau Jia Yi* Date: 24/08/2021

(2) Legal Name of Inventor: **KOK HONG SOON**

Signature: *Soon Kok Hong* Date: 24/08/2021

(3) Legal Name of Inventor: **TEJEASH DURAIMANICKAM**

Signature: *Tejash Duraimanickam* Date: 25/08/2021

(4) Legal Name of Inventor: **JIN HOE PHUA**

Signature: *Phua Jin Hoe* Date: 24/08/2021